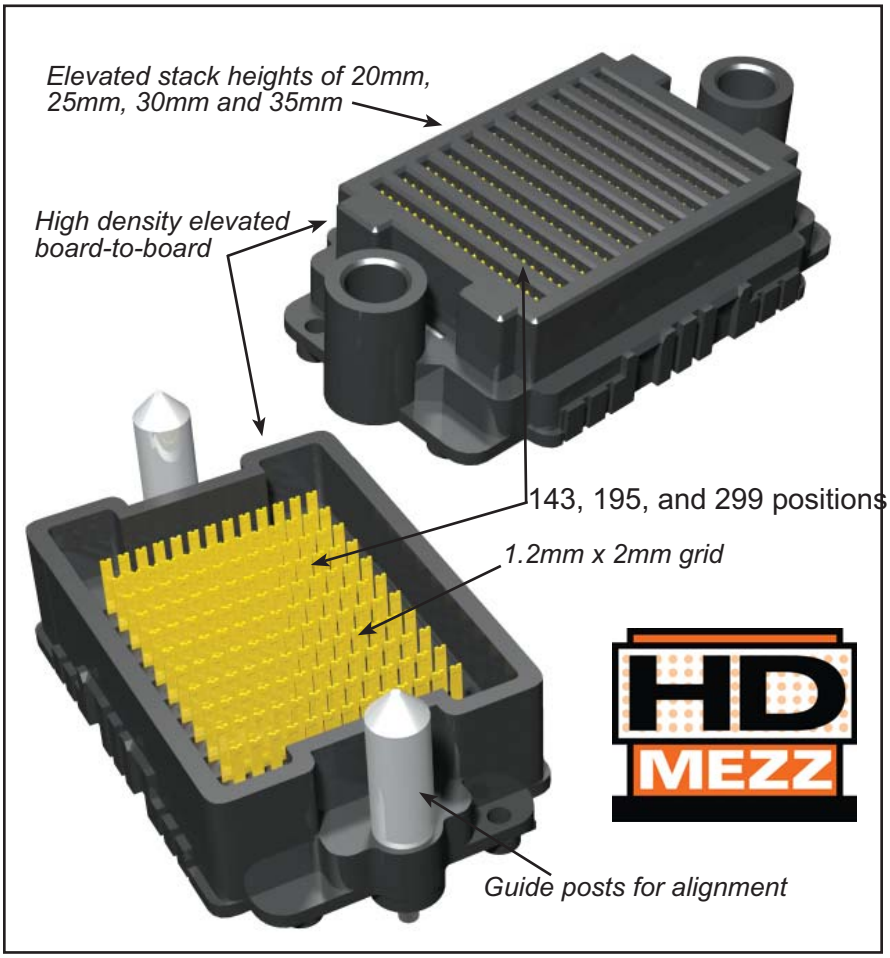
HD Mezz

The HD Mezz performs at 9.0 GHz/pair at a 20mm stack

HD Mezz is a 1.2mm x 2mm grid interconnect system for elevated, high speed board-to-board applications. The high density array's open pin field design allows both single-ended or differential pair routing. When routed differentially, HD Mezz is rated at 9.0 GHz/pair at a 20mm stack height. The HD Mezz is sourced by both Samtec and Molex Incorporated.



The HDAM/HDAF Series (HD Mezz) is available in:

- 143, 195, and 299 positions
- 20mm, 25mm, 30mm, and 35mm standard stack heights
- Custom heights available

Dual wipe contacts provide a reliable mating interface and the 1.2mm grid is ideal for applications where PCB real estate is limited.

The HD Mezz has the option to contain lead or a lead-free tin alloy, to meet RoHS compliancy requirements. The HDAM/HDAF Series also incorporates guide posts as a standard feature to aid in alignment.

Final Inch® information is available for the HD Mezz system. Final Inch® is a "reference design" for one of the most difficult design issues on the board - the Breakout Region (BOR) around the connector. Samtec can provide empirical TDR and frequency domain data, test boards, and validated electrical models for the HD Mezz system. This information is a time saving and unmatched service in the interconnect industry. Visit www.finalinch.com for more information.

Other high density, high speed array interconnects include:

- SEARAY™
- DP Array™
- SamArray®

*HD Mezz is a trademark of Molex Incorporated.